

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

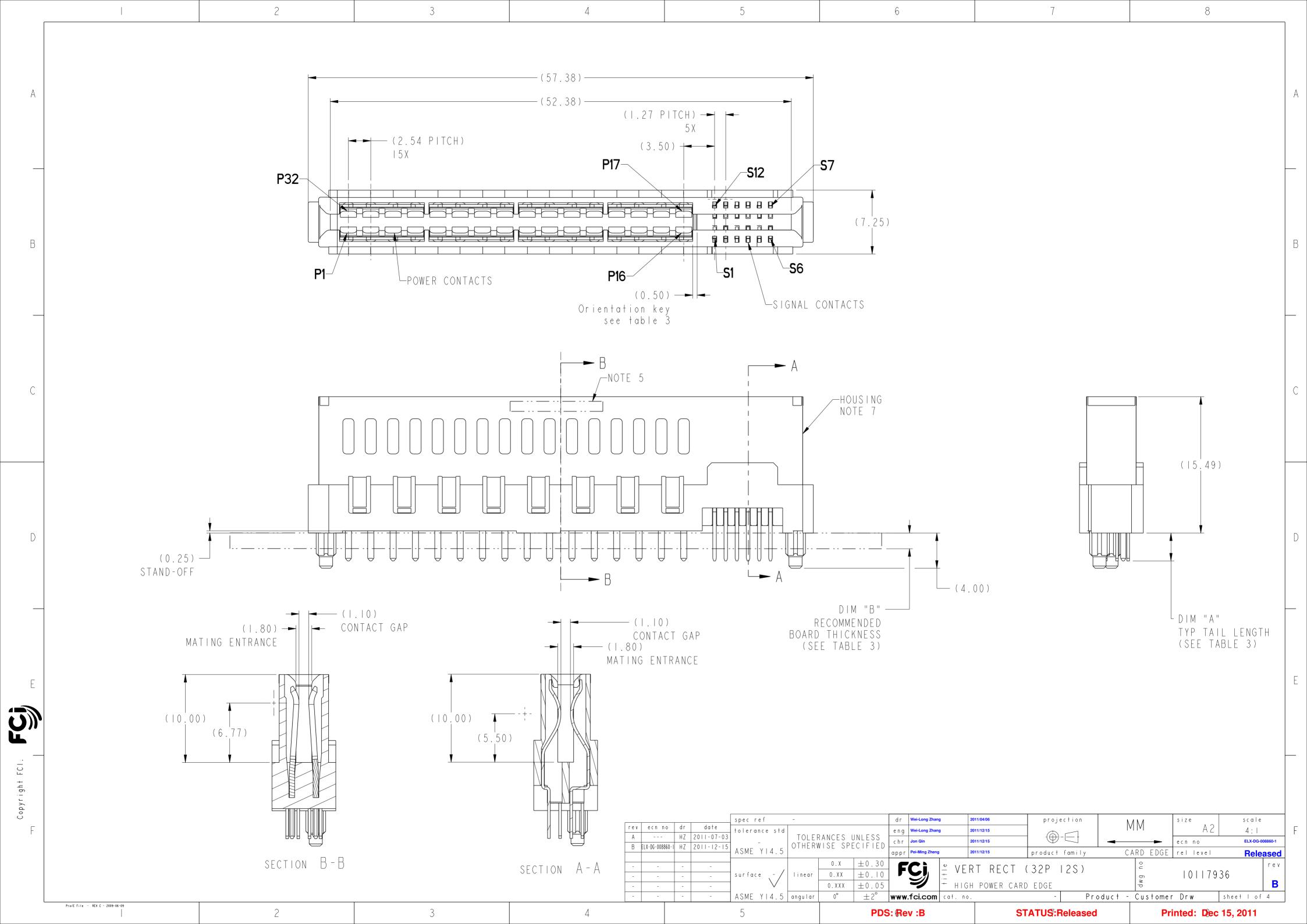
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

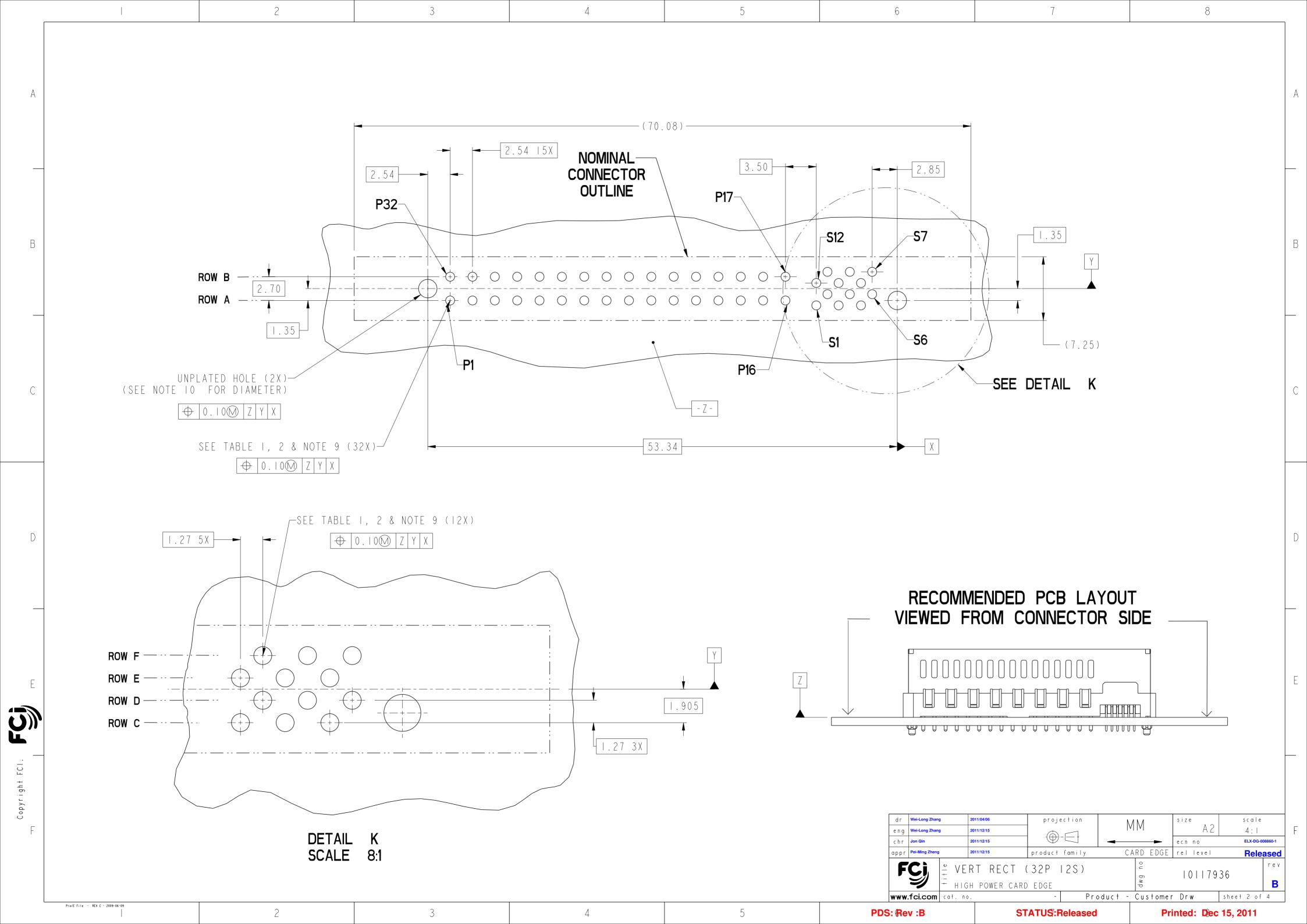
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

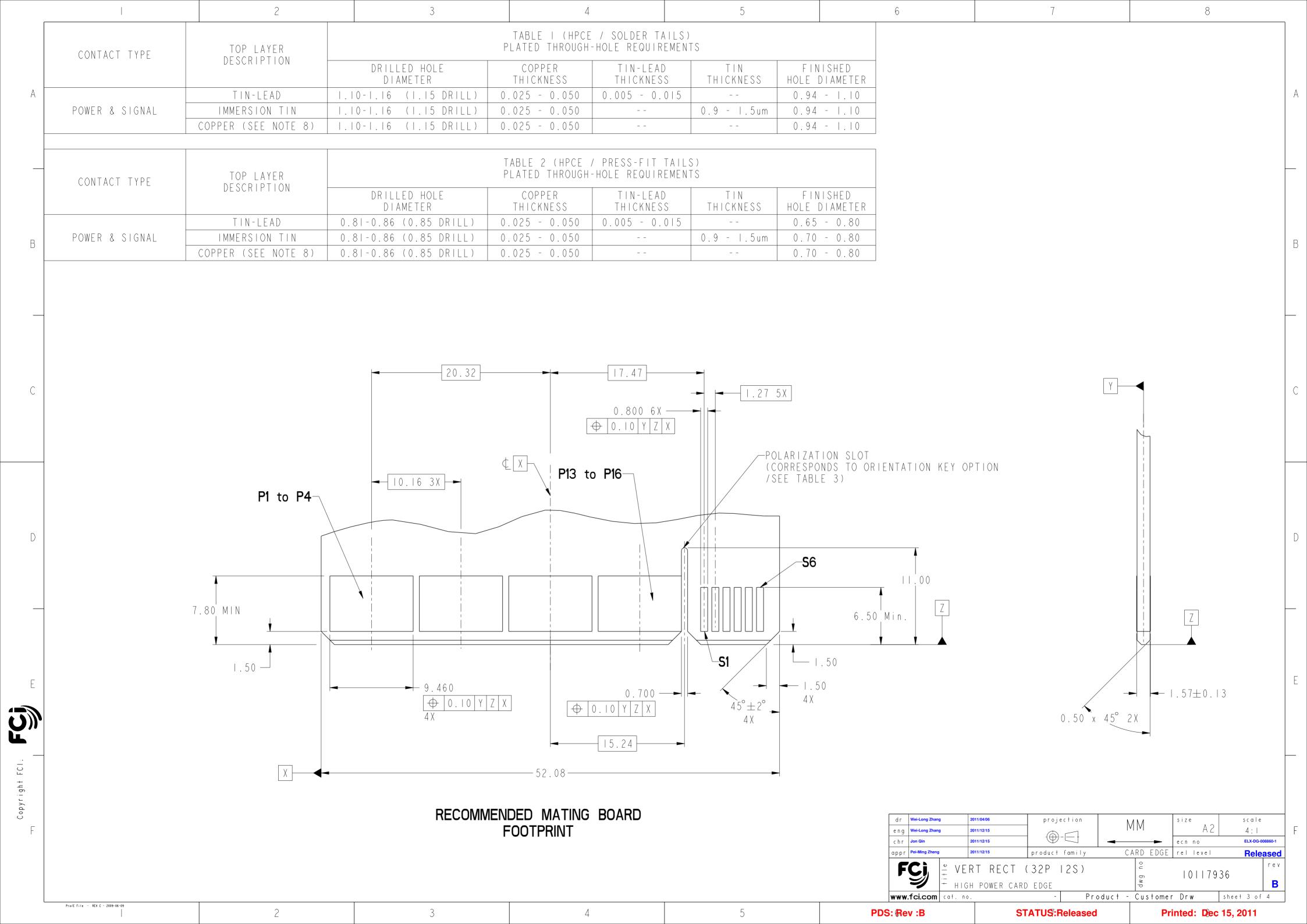












			2	3	4	5	6	7	8
		H P C E	E PART NUMBER	(TABLE 3)					
F	PART NUMBER	T A I L T Y P E	ORIENTATION KEY	DIM "A" TYPICAL TAIL LENGTH	DIM "B" RECOMMENDED BOARD THICKNESS				
01	17936-001LF	SOLDER	YES						
101	17936-002LF	SOLDER	NO	- 3.17 ±0.25	1.59 - 2.38				
0	17936-003	PRESS-FIT	YES						
0 1	17936-003LF	PRESS-FIT	YES		1.6				
0	17936-004	PRESS-FIT	NO	- 3.17 ±0.25	MIN				
0	17936-004LF	PRESS-FIT	NO						
		R MATERIALS: SING: HIG	H TEMPFRATURF THF	RMAL PLASTIC. BLACK					
	CONTACT 3. PRODUCT 4. APPLICAT	TACTS: HIG FINISH REF. GS SPECIFICATION: TION SPECIFICAT	H PERFORMANCE COP G-12-604 SECTION 5 GS-12-604. TION: GS-20-128.		N AREA SHOWN.				
			ECIFICATION GS-14 WITHSTAND EXPOSU		RATURE				
	HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN. (8). COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHE				HER AREAS.				
	9.) ALL HOLE SIZES ARE FINISHED HOLE SIZES.					dr Wei-Long Zhang	2011/04/06 projection		
	(10) MOUNT,ING	G HOLES ARE UNP						projection	1 0 1 7 ^
	Ø 2 Ø 2	2.40 +/- 0.1 FOI 2.10 +/- 0.1 FOI	LATED R PRESS-FIT TAILS R SOLDER TAILS				chr Jon Qin appr Pei-Ming Zheng	2011/12/15	Size Scale 4: